Supplier Name: Amkor Technology, Inc.
Company Address: Seoul & Gwangju city in Korea
Responder Contact Name: Miseon Hong.
Responder Contact Phone: 82-2-460-5327
Responder Contact email: mshong@amkor.co.kr
Responder Title: ESH engineer
Date of Response: 15-Oct

Responder Signature:

Instructions

Suppliers must provide the identity and % weight of ALL substances of very high concern (SVHC) present in products supplied to Maxim. SVHCs are defined by REACH Article 57 and in accordance with Directive 67/548/EEC. The criteria is set out in REACH Annex XIII. For more information see http://ec.europa.eu/environment/chemicals/reach/reach_intro.htm .

The list of SVHC substances is only for the currently known candidate listing as of Oct 1 2008. Additional updates to this listing are expected and additional requests for data on those new substances as added will be sent.

Data is to supplied for each material type/formulation used in our products. Where multiple suppliers are used, worse case data (highest value) should be shown. Examples: Material Type = Mold Compound, Name/Formula = Sumitomo EME-G600. Material Type = Leadframe, Name/Formula = Cu alloy C194.

Where there is no content of the substance, enter 0%.
Insert additional rows as needed to reflect content of substances per material used.

Amkor's Comment :
As of the date of this survey and to the best of our knowledge,the substances of concern are not knowingly present in the supplied Materials except for the items iindicated below , although they may be present as adventitious trace impurities. This declaration is provided in good faith and is based on available information sources from raw material suppliers.

		% Weight of Substance/CAS number																
		Anthracene (CAS No. 120-12-7)	4,4'-diaminodiphenylmethane (CAS No. 101-77-9)	Dibutyl phthalate (DBP) (CAS No. 84-74-2)	Cyclododecane (CAS No. 294-62-2)	Cobalt dichloride (CAS No. 7546-79-9)	Diarsenic pentaoxide (CAS No. 1303-28-2)	Diarsenic trioxide (CAS No. 1327-53-3)	Sodium dichromate, dihydrate (CAS No. 7789-12-0)	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) (CAS No. 81-15-2)	Bis (2-ethyl(hexyl)phthalate) (DEHP) (CAS No. 117-81-7)	Hexabromocyclododecane (HBCDD) (CAS No. 25637-99-4)	Short chain chlorinated paraffins (SCCPs) (CAS No. 85535-84-8)	Bis(tributyltin)oxide (CAS No. 56-35-9)	Lead hydrogen arsenate (CAS No. 7784-40-9)	Triethyl arsenate (CAS No. 15606-95-8)	Benzyl butyl phthalate (BBP) (CAS No. 85-68-7)
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G700	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G700L	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach																	
Material Name/Formula	ABLESTIK 8290	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach																	
Material Name/Formula	ABLESTIK 8361J	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Bond Wire																	
Material Name/Formula	AU 1.0 MIL-(LOW LOOP)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Plating-External terminations																	
Material Name/Formula	Rohm&haas -Matte Tin option (ST-380 process)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Plating-External terminations																	
Material Name/Formula	Hojin Platec- SnBi option	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	Cu alloy C194.	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	Cu alloy C7025.	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	Cu alloy E23Z.	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Leadframe																	
Material Name/Formula	Cu alloy C18045 (= E64T).	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach																	
Material Name/Formula	ABLESTIK 2300	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Die Attach																	
Material Name/Formula	AMK-02	0	0	0.24%	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	LID ADHESIVE																	
Material Name/Formula	DOW7920	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	LID ADHESIVE																	
Material Name/Formula	ABLESTIK 2000T	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	NITTO GE100LFCS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Mold Compound																	
Material Name/Formula	Sumitomo EME-G770	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Marking Ink																	
Material Name/Formula	TPC 410 WHITE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Marking Ink																	
Material Name/Formula	MARKEM 4405 BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	ENCAPSULANT																	
Material Name/Formula	CB0260-AT	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	DAM																	
Material Name/Formula	HYSOL FP-4451	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Bond Wire																	
Material Name/Formula	AU 1.0 MIL-(HP WIRE)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Bond Wire																	
Material Name/Formula	AU 1.0 MIL-(HTS WIRE)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Ball																	
Material Name/Formula	SN63/PB37	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Ball																	
Material Name/Formula	SN96.5/AG3.0/CU0.5	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Solder Ball																	
Material Name/Formula	SN95.5/AG4.0/CU0.5	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Heat Slug																	
Material Name/Formula	Black Oxide	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrates - Core laminate																	
Material Name/Formula	HL832HS	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrates - Core laminate																	
Material Name/Formula	HL832	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Material Type	Substrates - Solder Mask																	
Material Name/Formula	AUS5	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0